

### Listing of Claims

~~Claims 1-14~~ (Canceled)

~~Claim 15~~<sup>1</sup> (Currently amended) A method for depositing a solderable finish on an electronic device substrate, the method comprising;

electrolytically depositing onto the substrate a metal from an electroplating composition that comprises ~~at least one or more~~ soluble metal salt, an electrolyte, at least ~~on one~~ grain refiner/stabilizer additive comprising one or more ~~non-aromatic compounds having  $\pi$  electrons~~ that can be delocalized hydroxylated gamma-pyrone compounds.

~~Claim 16~~<sup>2</sup> (Original) The method of claim ~~15~~<sup>1</sup> wherein the metal salt comprises tin.

~~Claim 17~~ (Canceled)

~~Claim 18~~<sup>3</sup> (Currently amended) The method of claim ~~15~~<sup>1</sup> wherein the grain refiner/stabilizer additive is present at ~~concentration-concentrations~~ of between about 2 mg and about 10,000 mg per liter of the electroplating composition.

~~Claim 19~~<sup>4</sup> (Currently amended) The method of claim ~~15~~<sup>1</sup> wherein the stabilizer additive is present at ~~concentration-concentrations~~ of between about 50 mg and about 2000 mg per liter of the electroplating composition.

~~Claim 20~~<sup>5</sup> (Original) The method of claim ~~15~~<sup>1</sup> further comprising a brightener agent.

~~Claim 21~~<sup>6</sup> (Original) The method of claim ~~15~~<sup>1</sup> wherein the composition further comprises a suppressor agent.

~~Claim 22~~<sup>7</sup> (Original) The method of claim ~~15~~<sup>1</sup> wherein the composition further comprises a leveler agent.

~~Claim 23~~<sup>8</sup> (Original) The method of claim ~~15~~<sup>1</sup> wherein the substrate is a printed circuit board substrate or semiconductor with one or more microvias.

~~Claim 24~~<sup>9</sup> (Original) The method of claim ~~15~~<sup>1</sup> wherein the substrate is a microchip module substrate.

~~Claim 25~~ (Canceled)

~~Claim 26~~ (Canceled)

~~Claim 27~~<sup>10</sup> (New) The method of claim ~~15~~<sup>1</sup> wherein the hydroxylated gamma-pyrone comprises Kojic acid, meconic acid, comenic acid, maltol, or ethylmaltol.

~~11.~~  
Claim ~~28~~ (New) The method of claim ~~15~~ wherein the soluble metal salt comprises a salt of tin, zinc, copper, nickel, gold, silver, bismuth, indium or antimony.

~~12.~~  
Claim ~~29~~ (New) The method of claim ~~15~~ wherein the metal is a tin alloy.

~~13.~~  
Claim ~~30~~ (New) The method of claim ~~29~~ wherein the tin alloy is an alloy of tin-silver or tin-copper.

~~14.~~  
Claim ~~31~~ (New) the method of claim ~~15~~ wherein the metal is a zinc alloy.